



The Thermal Management Industry International Summit: *coolingZONE 13*

coolingZONE-13 Thermal Management Industry International Summit is the premiere engineering conference for the thermal management industry. Three days of engineering presentations, a full exhibitor pavilion, and networking with other technologists, engineers and scientists make this a must attend event. **Join us in Boston, October 21-23, 2013 for coolingZONE-13.**

Keynote Speakers:

Dr. Vincent Manno, Provost and Dean of Faculty at Olin College: *"Redefining Engineering as a Profession of Innovation"*

Dr. Marc Hodes, Tufts University: *"Galinstan-Based Cooling of Microelectronics: Beyond Tuckerman and Pease?"*

Dr. Kaveh Azar, CEO, Advanced Thermal Solutions: *"State of the Art in Thermal Management - From Vacuum Tube to Super Computers"*

Summit Hours:

October 21, Monday 11AM (registration opens) till 6PM exhibitor reception to follow

October 22, Tuesday 8AM to 6PM

October 23, Wednesday 8AM to 12PM, with lunch and Summit adjourn at 1:30PM. The schedule is posted on coolingZONE.com

See you at **coolingZONE-13**, the Thermal Management event of the year!

Don't miss out hearing the leaders of technology!
15% off discount code (CZ2013-MSPS41)

We've got a great program planned this year and we do hope you'll attend, here is a list of the speakers and topics:

Dr. Rich Hill, Laird *"Meeting the challenges facing thermal materials suppliers through a new approach to technology, innovation, and intellectual property"*

Bill Pfeifer, sp3 Diamond *"The Commercial Use of Diamond Heat Spreader Material for Thermal Management/Heat Transfer Challenges"*

Dr. Philip Blazdell, T-Global Technologies *"Passive Thermal Management - Challenges and Directions For A Lower Cost of Ownership Solution"*

Dr. Sukhvinder Kang, CTO, Aavid-Thermalloy Technologies *"New technologies maximize the cooling potential of heat sinks"*

Ruben Bons, CD-Adapco *"Planes, Trains, and Automobiles...& Electronics?"*

Dennis Downs, Colder Products *"Attributes of Highly Effective Quick Disconnect Couplings for Liquid Cooling of Computers and Servers"*

Marie Ross, Future Facilities *"Thinking outside the box: server design for data center optimization"*

Dr. PS Lee, GCore Labs *"High Performance, Energy Efficient Oblique Fin Liquid Cooling Technology for the Effective Thermal Management of EV/HEV Battery Pack and Power Electronics"*

Jim Burnett, Aspen Systems *"Advances in Miniaturized Vapor Compression Electronics Cooling"*

Yuya Ando, Cradle-CFD *"Simulating The Future: How to Tackle Next Generation Thermal Challenges with Time Efficient Methods and Techniques"*

Jim VanGilder, P.E., APC by Schneider Electric *"Fast CFD for Data Center Cooling Design"*

Dr. Camil Ghiu, Advanced Thermal Solutions *"Driving Towards 0.1 Degree C per Watt in Compact Air Cooled Systems: Advancements in Flow Management and Air Jet Impingement Cooling"*

Sam Bhayani, SinkPad *"Challenges and Solutions in LED and Solid State Lighting Thermal Management"*

